Date: 2024-12-30

FCC ID: 2ABRU-LE2340RGE

Dear Sir/Madam,

We, Guangzhou BDE Technology Inc. *Hereby declares the following statement for Innovation, Science and Economic Development for the models mentioned as below:*

Product name: BDE BLE Module Based on CC2340R

Models: BDE-LE2340R52GEA32, BDE-LE2340R52GEU32, BDE-LE2340R52GEN32, BDE-LE2340R52GEA0, BDE-LE2340R52GEU0, BDE-LE2340R52GEN0, BDE-LE2340R52GEA32-IN, BDE-LE2340R52GEU32-IN, BDE-LE2340R52GEN32-IN, BDE-LE2340R52GEA0-IN, BDE-LE2340R52GEU0-IN, BDE-LE2340R52GEN0-IN,

BDE-LE2340R21GEA32, BDE-LE2340R21GEU32, BDE-LE2340R21GEN32, BDE-LE2340R21GEA0, BDE-LE2340R21GEU0, BDE-LE2340R21GEN0, BDE-LE2340R21GEA32-IN, BDE-LE2340R21GEU32-IN, BDE-LE2340R21GEN32-IN, BDE-LE2340R21GEA0-IN, BDE-LE2340R21GEU0-IN, BDE-LE2340R21GEN0-IN

Model Number	Orderable Part Number	Chipset	Flash (KB)	SRAM (KB)	Antenna on 2.4G	On-Board SPI Nor Flash Support	Operating Temperature (°C)
BDE- LE2340 RGE	BDE-LE2340R52GEA32	CC2340R 52GE	512	36	PCB Trace Antenna	32Mbit	-40°C ∼85°C
	BDE-LE2340R52GEU32				U.FL Connector		
	BDE-LE2340R52GEN32				ANT Pin		
	BDE-LE2340R52GEA0				PCB Trace Antenna	Not Included	
	BDE-LE2340R52GEU0				U.FL Connector		
	BDE-LE2340R52GEN0				ANT Pin		
	BDE-LE2340R52GEA32-IN				PCB Trace Antenna	32Mbit	-40℃ ~ 105℃
	BDE-LE2340R52GEU32-IN				U.FL Connector		
	BDE-LE2340R52GEN32-IN				ANT Pin		
	BDE-LE2340R52GEA0-IN				PCB Trace Antenna	Not Included	
	BDE-LE2340R52GEU0-IN				U.FL Connector		
	BDE-LE2340R52GEN0-IN				ANT Pin		
	BDE-LE2340R21GEA32	CC2340R 21GE	256	28	PCB Trace Antenna	32Mbit	40°C ∼85°C
	BDE-LE2340R21GEU32				U.FL Connector		
	BDE-LE2340R21GEN32				ANT Pin		
	BDE-LE2340R21GEA0				PCB Trace Antenna	Not Included	
	BDE-LE2340R21GEU0				U.FL Connector		
	BDE-LE2340R21GEN0				ANT Pin		
	BDE-LE2340R21GEA32-IN				PCB Trace Antenna	32Mbit	40℃ ~ 105℃
	BDE-LE2340R21GEU32-IN				U.FL Connector		
	BDE-LE2340R21GEN32-IN				ANT Pin		
	BDE-LE2340R21GEA0-IN				PCB Trace Antenna	Not Included	
	BDE-LE2340R21GEU0-IN				U.FL Connector		
	BDE-LE2340R21GEN0-IN				ANT Pin		

Identities and differences:

The above models have same PCB board and structure, The differences between the above models mainly lie in the main chip model(note: only the Flash and SRAM sizes are different between the main chip models), antenna interface location, operating temperature, and whether an external 32Mbit SPI Flash is configured.

Sincerely,

Jam

(Signed)
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